

Appl. No. 10/711,882
Amdt. dated March 29, 2006
Reply to Office action of January 19, 2006

Amendments to the Claims:

Listing of Claims:

Claim 1 (original) A wafer carrier for carrying a wafer, comprising:

- 5 a transparent base; and
 a conducting layer positioned on a bottom surface of the transparent
 base; wherein the wafer carrier is attracted by an electrostatic chuck
 via the conducting layer.

10 Claim 2 (original) The wafer carrier of claim 1, wherein the transparent
 base has dimensions similar to that of the wafer.

 Claim 3 (original) The wafer carrier of claim 1, wherein the transparent
 base is a glass wafer.

15 Claim 4 (original) The wafer carrier of claim 1, wherein the transparent
 base is a quartz wafer.

 Claim 5 (original) The wafer carrier of claim 1 further comprising a
 bonding layer positioned on a top surface of the wafer carrier for bonding
20 the wafer and the transparent base together.

 Claim 6 (original) The wafer carrier of claim 5, wherein the bonding layer
 is selected from the group consisting of double-sided tape, ultra violet tape,
 thermal sensitive tape, photo resist, and wax.

25 Claim 7 (currently amended) The wafer carrier of claim 1, wherein ~~the~~
 ~~wafer carrier is attracted by an electrostatic chuck via the conducting layer~~
 ~~so that~~ the wafer is transferred and undergoes at least a semiconductor

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process.

Claim 8 (original) The wafer carrier of claim 7, wherein the semiconductor
process is a double-sided process, and the wafer comprises at least an
5 alignment mark.

Claim 9 (original) The wafer carrier of claim 8, wherein the conducting
layer is a transparent conducting layer.

10 Claim 10 (original) The wafer carrier of claim 8, wherein the conducting
layer is a non-transparent conducting layer having at least an exposed
region corresponding to the alignment mark.

Claim 11 (original) The wafer carrier of claim 10, wherein the
15 non-transparent conducting layer comprises a plurality of conducting
patterns connected with each other.

Claim 12 (currently amended) A wafer carrier adapted for use in a
double-sided process for carrying a wafer, comprising:

20 a transparent base;
a conducting layer positioned on a bottom surface of the transparent
base, wherein the wafer carrier is attracted by an electrostatic chuck
via the conducting layer; and
a bonding layer positioned on a top surface of the transparent base for
25 bonding the wafer and the transparent base.

Claim 13 (original) The wafer carrier of claim 12, wherein the transparent
base has dimensions similar to that of the wafer.

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Claim 14 (original) The wafer carrier of claim 12, wherein the transparent base is a glass wafer.

5 Claim 15 (original) The wafer carrier of claim 12, wherein the transparent base is a quartz wafer.

Claim 16 (original) The wafer carrier of claim 12, wherein the bonding layer is selected from the group consisting of double-sided tape, ultra
10 violet tape, thermal sensitive tape, photo resist, and wax.

Claim 17 (currently amended) The wafer carrier of claim 12, wherein ~~the wafer carrier is attracted by an electrostatic chuck via the conducting layer so that~~ the wafer is transferred and undergoes the double-sided process.
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Claim 18 (original) The wafer carrier of claim 17, wherein the wafer comprises at least an alignment mark.

Claim 19 (original) The wafer carrier of claim 18, wherein the conducting
20 layer is a transparent conducting layer.

Claim 20 (original) The wafer carrier of claim 18, wherein the conducting layer is a non-transparent conducting layer having at least an exposed region corresponding to the alignment mark.
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Claim 21 (original) The wafer carrier of claim 12, wherein the non-transparent conducting layer comprises a plurality of conducting

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patterns connected with each other.